


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/21/12658	
1.3 Title of PCN	L4979Dx, L4988Dx, L4993Dx, L4989Dx (UH01, UH21, UH44, UH71): Assembly and Final Test Transfer to Bouskoura	
1.4 Product Category	see list	
1.5 Issue date	2021-03-26	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Vito GRAZIANO
2.1.2 Marketing Manager	Angelo MOTTESE
2.1.3 Quality Manager	Marcello Donato MENCHISE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Recipient: ST Shenzhen Plant (China) Destination: ST Bouskoura Plant (Morocco)

4. Description of change

	Old	New
4.1 Description	Assembly and Final Test in Shenzhen (China)	Assembly and Final Test in Bouskoura (Morocco)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	Service and Capacity improvement. Manufacturing process optimization
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Dedicated Finished Goods Codes
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7. Timing / schedule

7.1 Date of qualification results	2021-09-30
7.2 Intended start of delivery	2021-10-31
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	L4979D013TR	
	L4979DTR-E	
	L4988DTR	
	L4989D013TR	
	L4993DTR	

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PRODUCT/PROCESS CHANGE NOTIFICATION

TITLE	L4979Dx, L4988Dx, L4993Dx, L4989Dx (UH01, UH21, UH44, UH71): Assembly and Final Test Transfer to Bouskoura																										
IMPACTED PRODUCTS	ST silicon lines UH01 – UH21 – UH44 – UH71 diffused in BCD4 technology and assembled in SO8 package																										
MANUFACT. STEP	Assembly and Electrical Final Test																										
INVOLVED PLANT	Recipient: ST Shenzhen Plant (China) Destination: ST Bouskoura Plant (Morocco)																										
CHANGE REASON	Service and Capacity improvement. Manufacturing process optimization																										
CHANGE DESCRIPTION	<p>Transfer of package assembly and electrical final test from current Shenzhen (China) to Bouskoura (Morocco) Plant. Package Bill of Material is subject to upgrade as per following table:</p> <table><tr><td></td><td>SHENZHEN</td><td>BOUSKOURA</td><td>Notes</td></tr><tr><td>GLUE</td><td>ABLESTIK 8601S-25</td><td>ABLESTIK 8601S-25</td><td>same</td></tr><tr><td>FRAME</td><td>94x125 Mt HD NiThPdAgAu</td><td>94x125 SSHD IDF SpAg</td><td>different</td></tr><tr><td>LEAD FINISHING</td><td>e4</td><td>e3</td><td>different</td></tr><tr><td>RESIN</td><td>SUMITOMO EME-G700KC</td><td>SUMITOMO EME-G700KC</td><td>same</td></tr><tr><td>WIRE</td><td>Au D1.0</td><td>Cu D1.0</td><td>different</td></tr></table>				SHENZHEN	BOUSKOURA	Notes	GLUE	ABLESTIK 8601S-25	ABLESTIK 8601S-25	same	FRAME	94x125 Mt HD NiThPdAgAu	94x125 SSHD IDF SpAg	different	LEAD FINISHING	e4	e3	different	RESIN	SUMITOMO EME-G700KC	SUMITOMO EME-G700KC	same	WIRE	Au D1.0	Cu D1.0	different
	SHENZHEN	BOUSKOURA	Notes																								
GLUE	ABLESTIK 8601S-25	ABLESTIK 8601S-25	same																								
FRAME	94x125 Mt HD NiThPdAgAu	94x125 SSHD IDF SpAg	different																								
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RESIN	SUMITOMO EME-G700KC	SUMITOMO EME-G700KC	same																								
WIRE	Au D1.0	Cu D1.0	different																								
TRACEABILITY	Dedicated Finished Good code (internal part number)																										
VALIDATION	<p>According to ZVEI Delta Qualification Matrix corresponding to following selected items:</p> <ul style="list-style-type: none">SEM-PA-04 Change of lead frame finishing material / area (internal)SEM-PA-08 Change of wire bondingSEM-PA-18 Move all or parts of production to a different assembly siteSEM-TF-01 Move of all or part of electrical wafer test and/or final test to a different test site <p>leading to the following reliability qualification plan:</p>																										



●	A2	THB	Temperature Humidity Bias or biased HAST
●	A3	AC	Autoclave or Unbiased HAST
●	A4	TC	Temperature Cycling
-	A5	PTC	Power Temperature Cycling
●	A6	HTSL	High Temperature Storage Life
●	B1	HTOL	High Temperature Operating Life
●	B2	ELFR	Early Life Failure Rate
●	C1	WBS	Wire Bond Shear
●	C2	WBP	Wire Bond Pull
●	C3	SD	Solderability
●	C4	PD	Physical Dimensions
●	C6	LI	Lead Integrity
●	E5	ED	Electrical Distribution
-	E10	SC	Short Circuit Characterization
●	F12	LF	Lead free
●			Whisker test
●			Parameter-Analysis: Comparison of current with changed device characterization, electrical distribution
●			For Cu Wire Products: Consider AEQ-Q006

Above plant is implemented with following exceptions:

- + A5 Power Temperature Cycling: not performed (not done during original qualification)
- + B2 Early Life Failure Rate: limited to one qualification lot (not relevant for package related aspects)
- + E10 Short Circuit Characterization: not performed (not done during original qualification) – current limit test I_{LIM} done at final test (100% production)

CURRENT PRODUCTS	Replaced by new version featuring new Plant and upgraded package
REPORTS	Activity in progress. Availability by end 2021-Q3



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : L4979Dx, L4988Dx, L4993Dx, L4989Dx (UH01, UH21, UH44, UH71): Assembly and Final Test Transfer to Bouskoura

PCN Reference : ADG/21/12658

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

L4993DTR	L4979D013TR	L4989D013TR
L4988D	L4988DTR	



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